Low-Voltage CMOS 16-Bit Transparent Latch

With 5 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX16373 is a high performance, non–inverting 16–bit transparent latch operating from a 2.3 V to 3.6 V supply. The device is byte controlled. Each byte has separate Output Enable and Latch Enable inputs. These control pins can be tied together for full 16–bit operation. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A $V_{\rm I}$ specification of 5.5 V allows MC74LCX16373 inputs to be safely driven from 5.0 V devices.

The MC74LCX16373 contains 16 D-type latches with 3-state 5.0 V-tolerant outputs. When the Latch Enable (LEn) inputs are HIGH, data on the Dn inputs enters the latches. In this condition, the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state outputs are controlled by the Output Enable ($\overline{\text{OEn}}$) inputs. When $\overline{\text{OE}}$ is LOW, the outputs are enabled. When $\overline{\text{OE}}$ is HIGH, the standard outputs are in the high impedance state, but this does not interfere with new data entering into the latches.

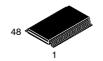
Features

- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5.4 ns Maximum t_{pd}
- 5.0 V Tolerant Interface Capability With 5.0 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 \text{ V}$
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- These are Pb-Free Devices*



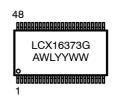
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TSSOP-48 DT SUFFIX CASE 1201

MARKING DIAGRAM



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Wee

WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

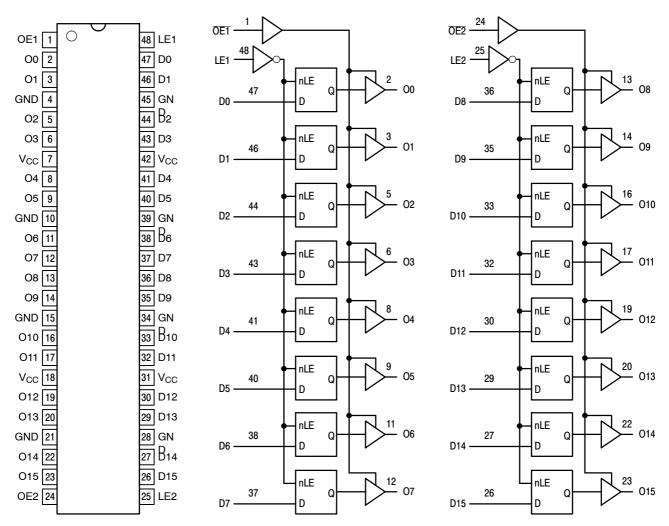


Figure 1. Pinout: 48-Lead (Top View)

Figure 2. Logic Diagram

Table 1. PIN NAMES

Pins	Function
OEn	Output Enable Inputs
LEn	Latch Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

TRUTH TABLE

	Inputs		Outputs		Inputs		Outputs
LE1	OE1	D0:7	O0:7	LE2	OE2	D8:15	O8:15
Х	Н	Х	Z	Х	Н	Х	Z
Н	L	L	L	Н	L	L	L
Н	L	Н	Н	Н	L	Н	Н
L	L	Х	O0	L	L	Х	O0

Н High Voltage Level L Low Voltage Level

High Impedance State

Z X High or Low Voltage Level and Transitions Are Acceptable; for I_{CC} reasons, DO NOT FLOAT Inputs

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX16373DT	TSSOP-48*	39 Units / Rail
MC74LCX16373DTG	TSSOP-48*	39 Units / Rail
MC74LCX16373DTR2	TSSOP-48*	2500 / Tape & Reel
M74LCX16373DTR2G	TSSOP-48*	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_{l} \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_0 \le +7.0$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Output in HIGH or LOW State. (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V _{CC}	Supply Voltage	Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage		0		5.5	V
Vo	Output Voltage	(HIGH or LOW State) (3-State)	0		V _{CC} 5.5	٧
I _{OH}	HIGH Level Output Current	$V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$			- 24 - 12 - 8	mA
l _{OL}	LOW Level Output Current	$V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$			+ 24 + 12 + 8	mA
T _A	Operating Free-Air Temperature		-55		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from	0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

^{*}This package is inherently Pb-Free.

^{1.} I_O absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -55°C	to +125°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		V
		2.7 V ≤ V _{CC} ≤ 3.6 V	2.0		1
V _{IL}	LOW Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	V
		2.7 V ≤ V _{CC} ≤ 3.6 V		8.0	1
V _{OH}	HIGH Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$	V _{CC} - 0.2		٧
		$V_{CC} = 2.3 \text{ V; } I_{OH} = -8 \text{ mA}$	1.8		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -18 \text{ mA}$	2.4		1
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -24 \text{ mA}$	2.2		1
V _{OL}	LOW Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.6	1
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	1
		V _{CC} = 3.0 V; I _{OL} = 16 mA		0.4	1
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	1
I _I	Input Leakage Current	$2.3 \text{ V} \le \text{V}_{\text{CC}} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}$		±5.0	μΑ
I _{OZ}	3-State Output Current	$2.3 \le V_{CC} \le 3.6 \text{ V}; \ 0V \le V_{O} \le 5.5 \text{ V};$ $V_{I} = V_{IH} \text{ or } V_{IL}$		±5.0	μΑ
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 5.5 V		10	μΑ
I _{CC}	Quiescent Supply Current	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		20	μΑ
		$2.3 \le V_{CC} \le 3.6 \text{ V}; 3.6 \le V_{I} \text{ or } V_{O} \le 5.5 \text{ V}$		±20	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	2.3 ≤ V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} − 0.6 V		500	μΑ

^{2.} These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS $t_R=t_F$ = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

			T _A = -55°C to +125°C						
			V _{CC} = 3.3 C _L =	V ± 0.3 V 50 pF	V _{CC} =	2.7 V 50 pF	V _{CC} = 2.5 C _L =	V ± 0.2 V 30 pF	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH}	Propagation Delay D _n to O _n	1	1.5 1.5	5.4 5.4	1.5 1.5	5.9 5.9	1.5 1.5	6.5 6.5	ns
t _{PLH}	Propagation Delay LE to O _n	3	1.5 1.5	5.5 5.5	1.5 1.5	6.4 6.4	1.5 1.5	6.6 6.6	ns
t _{PZH}	Output Enable Time to High and Low Level	2	1.5 1.5	6.1 6.1	1.5 1.5	6.5 6.5	1.5 1.5	7.9 7.9	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	1.5 1.5	6.0 6.0	1.5 1.5	6.3 6.3	1.5 1.5	7.2 7.2	ns
t _s	Setup Time, HIGH or LOW D ⁿ to LE	3	2.5		2.5		3.0		ns
t _h	Hold Time, HIGH or LOW Dn to LE	3	1.5		1.5		2.0		ns
t _w	LE Pulse Width, HIGH	3	3.0		3.0		3.5		ns
toshl toslh	Output-to-Output Skew (Note 3)			1.0 1.0					ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

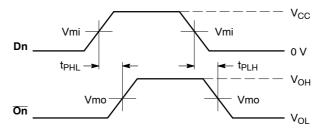
DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OLP}	Dynamic LOW Peak Voltage (Note 4)	$\begin{array}{c} V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V} \\ V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V} \end{array}$		0.8 0.6		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		-0.8 -0.6		V

^{4.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

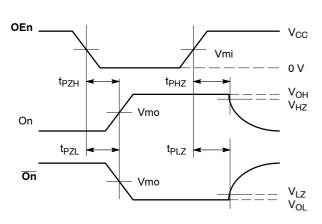
CAPACITIVE CHARACTERISTICS

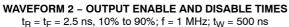
Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	20	pF

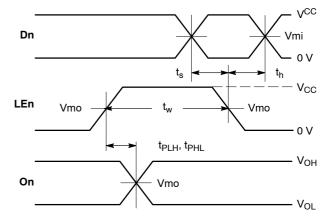


WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$







WAVEFORM 3 – LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn to LE SETUP AND HOLD TIMES

 t_R = t_F = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns except when noted

Figure 3. AC Waveforms

Table 2. AC WAVEFORMS

		V _{CC}					
Symbol	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V				
Vmi	1.5 V	1.5 V	V _{CC} / 2				
Vmo	1.5 V	1.5 V	V _{CC} / 2				
V_{HZ}	V _{OL} + 0.3 V	V _{OL} + 0.3 V	V _{OL} + 0.15 V				
V_{LZ}	V _{OH} – 0.3 V	V _{OH} – 0.3 V	V _{OH} – 015 V				

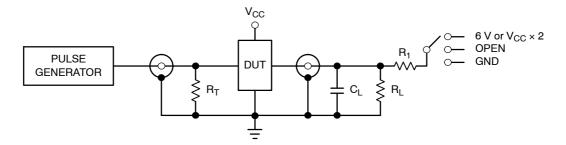


Figure 4. Test Circuit

Table 3. TEST CIRCUIT

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V $_{CC}$ = 3.3 \pm 0.3 V 6 V at V $_{CC}$ = 2.5 \pm 0.2 V
Open Collector/Drain t _{PLH} and t _{PHL}	6 V
t _{PZH} , t _{PHZ}	GND

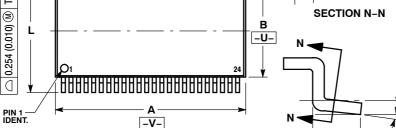
 C_L = 50 pF at V_{CC} = 3.3 \pm 0.3 V or equivalent (includes jig and probe capacitance) C_L = 30 pF at V_{CC} = 2.5 \pm 0.2 V or equivalent (includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50 Ω)

PACKAGE DIMENSIONS

TSSOP-48 CASE 1201-01 ISSUF B 0.12 (0.005) M T U S V S SECTION N-N

NOTES:

6.



DETAIL E 0.25 (0.010)

MILLIMETERS INCHES DIM MIN MAX MIN MAX Α 12.40 12.60 0.488 0.496 B 6.00 6.20 0.236 0.244 1.10 0.043 D 0.05 0.15 0.002 0.006 0.020 0.030 0.50 0.75 G 0.50 BSC 0.0197 BSC Н 0.37 0.015 0.09 0.20 0.004 J1 0.09 0.16 0.004 0.006 Κ 0.17 0.27 0.007 0.011 K1 0.17 0.23 | 0.007 | 0.009 0.313 0.325 7.95 8 0 0 0 8 °

1. DIMENSIONING AND TOLERANCING PER

CONTROLLING DIMENSION: MILLIMETER.

DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
DIMENSION K DOES NOT INCLUDE DAMBAR

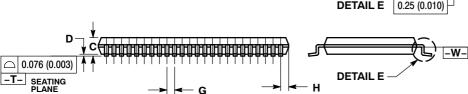
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PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT

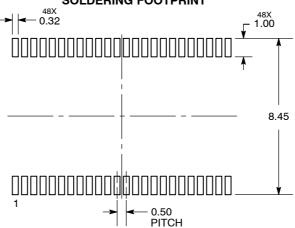
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RECOMMENDED **SOLDERING FOOTPRINT**



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